

Title (en)

Process for improving the adhesion of metallic particles on a carbon substrate

Title (de)

Verfahren für die Verbesserung der Haftung von metallischen Partikeln auf einen Kohlenstoffsubstrat

Title (fr)

Procédé pour améliorer l'adhérence de particules métalliques sur un substrat carboné

Publication

EP 0982412 A1 20000301 (FR)

Application

EP 99401992 A 19990805

Priority

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Abstract (en)

[origin: US6261632B1] The present invention relates to a process for improving the adhesion of metal particles to a carbon substrate, characterized in that, before the said metal particles are deposited on the carbon substrate, the said substrate is treated in an alkaline medium at a temperature of between 50° C. and 100° C. in a stream of a gas containing oxygen.

Abstract (fr)

La présente invention concerne un procédé pour améliorer l'adhérence de particules métalliques sur un substrat carboné, caractérisé en ce que, avant dépôt desdites particules métalliques sur le substrat carboné, ledit substrat est traité en milieu alcalin à une température comprise entre 50°C et 100°C sous courant d'un gaz contenant de l'oxygène.

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Citation (search report)

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